



Fully automatic assembling of electronic components

Zakład Elektronicznych Urządzeń Pomiarowych POZYTON Sp. z o.o. is committed to offering assembly of components for complete electronic devices.

Our offer contain assembling and realization of electronic components based on technology:

- superficial – SMD components (one and two-sided),
- mixed – SMD components and mixed (one and two-sided assembling),
- threaded

In addition our offer contain:

- elaborating projects of printed circuit boards,
- preparing of technology documentation,
- testing and activating of all components,
- assembling of completely done devices,
- packing of ready to use items.



Our equipment gives possibility of assembling SMD components:

- passive components: from 0603 to 2010, MELF, MINIMELF, SMT-A, SMT-B, SMT-C and others,
- passive components: QFP, SOIC, SO, SOP, TSSOP with pitch of 0,5 mm (possibility of wider pitch),
- active components: SOD, MELF, MINIMELF, SOT-23, SOT-223, D-PACK, PLCC 20 to PLCC 84, and others.

Short description of the technology process:

Infliction of soldering paste	- screen process,
Assembling of SMD components	- automatic machine with screen system,
Soldering of SMD components	- convection-type furnace,
Separation of multi blocks	- parting die,
Arranging of threaded components	- laser supporting devices,
Soldering of threaded components	- by double soldering or manually,
Optical controlling	- microscope, magnifying glass,
Functionality testing	- test apparatus supplied by client or custom designed,
Correcting during the assembly	- soldering station for reworking, hot air.



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